LM160/LM360 High Speed Differential Comparator

Check for Samples: LM160, LM360

FEATURES

- Guaranteed high speed: 20 ns max
- Tight delay matching on both outputs
- Complementary TTL outputs
- High input impedance
- Low speed variation with overdrive variation
- Fan-out of 4
- Low input offset voltage
- Series 74 TTL compatible

DESCRIPTION

The LM160/LM360 is a very high speed differential input, complementary TTL output voltage comparator with improved characteristics over the µA760/µA760C, for which it is a pin-for-pin replacement. The device has been optimized for greater speed, input impedance and fan-out, and lower input offset voltage. Typically delay varies only 3 ns for overdrive variations of 5 mV to 400 mV.

Complementary outputs having minimum skew are provided. Applications involve high speed analog to digital convertors and zero-crossing detectors in disk file systems.

CONNECTION DIAGRAMS

TO-99 Package

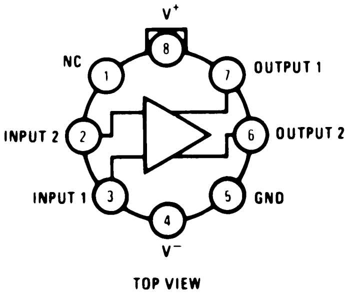

Figure 1. Package Number LMC0008C (1)

SOIC or PDIP Package

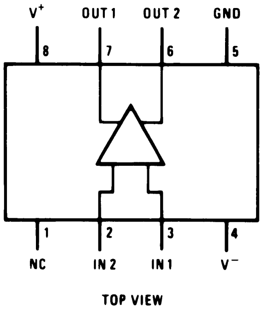

Figure 2. Package Number D0008A or P0008E

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(1) Also available in SMD# 5962-8767401

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings (1) (2)

Positive Supply Voltage		+8V
Negative Supply Voltage		−8V
Peak Output Current		20 mA
Differential Input Voltage		±5V
Input Voltage		$V^+ \geq V_{IN} \geq V^-$
ESD Tolerance (3)		1600V
Operating Temperature Range	LM160	−55°C to +125°C
	LM360	0°C to +70°C
Storage Temperature Range		−65°C to +150°C
Lead Temperature	(Soldering, 10 sec.)	260°C
Soldering Information		
PDIP Package	Soldering (10 seconds)	260°C
SOIC Package	Vapor Phase (60 seconds)	215°C
	Infrared (15 seconds)	220°C
See AN-450 “Surface Mounting Methods and Their Effect on Product Reliability” for other methods of soldering surface mount devices.		

(1) The device may be damaged if used beyond the maximum ratings.
(2) Refer to RETS 160X for LM160H, LM160J-14 and LM160J military specifications.
(3) Human body model, 1.5 kΩ in series with 100 pF.

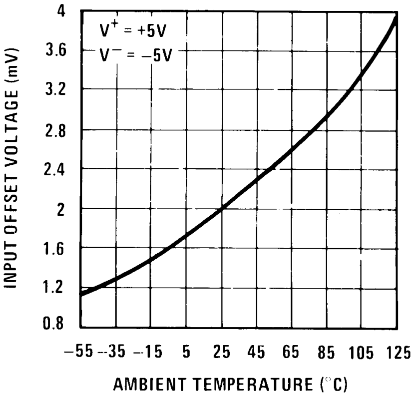
Electrical Characteristics

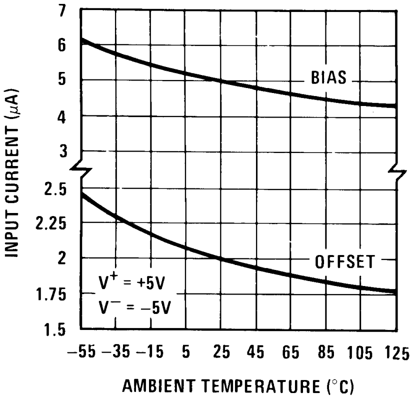
($T_{MIN} \leq T_A \leq T_{MAX}$)

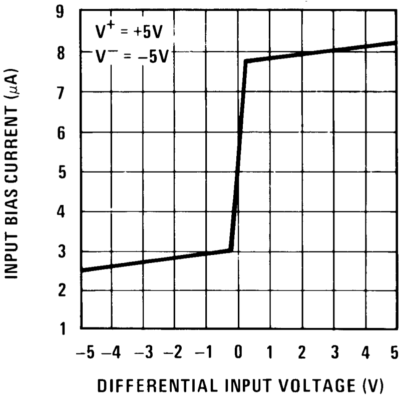
Parameter	Conditions	Min	Typ	Max	Units
Operating Conditions					
Supply Voltage V_{CC}^+		4.5	5	6.5	V
Supply Voltage V_{CC}^-		−4.5	−5	−6.5	V
Input Offset Voltage	$R_S \leq 200\Omega$		2	5	mV
Input Offset Current			0.5	3	μA
Input Bias Current			5	20	μA
Output Resistance (Either Output)	$V_{OUT} = V_{OH}$		100		Ω
Response Time	$T_A = 25°C$, $V_S = \pm5V$ (1) (2)		13	25	ns
	$T_A = 25°C$, $V_S = \pm5V$ (3) (2)		12	20	ns
	$T_A = 25°C$, $V_S = \pm5V$ (4) (2)		14		ns
Response Time Difference between Outputs					
(t_{pd} of $+V_{IN1}$) − (t_{pd} of $-V_{IN2}$)	$T_A = 25°C$ (1) (2)		2		ns
(t_{pd} of $+V_{IN2}$) − (t_{pd} of $-V_{IN1}$)	$T_A = 25°C$ (1) (2)		2		ns
(t_{pd} of $+V_{IN1}$) − (t_{pd} of $+V_{IN2}$)	$T_A = 25°C$ (1) (2)		2		ns
(t_{pd} of $-V_{IN1}$) − (t_{pd} of $-V_{IN2}$)	$T_A = 25°C$ (1) (2)		2		ns
Input Resistance	f = 1 MHz		17		kΩ
Input Capacitance	f = 1 MHz		3		pF
Average Temperature Coefficient of Input Offset Voltage	$R_S = 50\Omega$		8		μV/°C
Average Temperature Coefficient of Input Offset Current			7		nA/°C
Common Mode Input Voltage Range	$V_S = \pm6.5V$	±4	±4.5		V
Differential Input Voltage Range		±5			V
Output High Voltage (Either Output)	$I_{OUT} = -320$ μA, $V_S = \pm4.5V$	2.4	3		V
Output Low Voltage (Either Output)	$I_{SINK} = 6.4$ mA		0.25	0.4	V
Positive Supply Current	$V_S = \pm6.5V$		18	32	mA
Negative Supply Current	$V_S = \pm6.5V$		−9	−16	mA

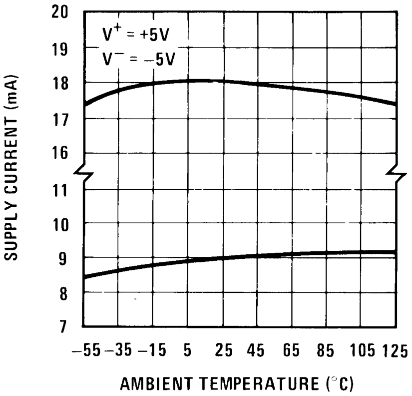
(1) Response time measured from the 50% point of a 30 mVp-p 10 MHz sinusoidal input to the 50% point of the output.
(2) Measurements are made in AC Test Circuit, Fanout = 1
(3) Response time measured from the 50% point of a 2 Vp-p 10 MHz sinusoidal input to the 50% point of the output.
(4) Response time measured from the start of a 100 mV input step with 5 mV overdrive to the time when the output crosses the logic threshold.

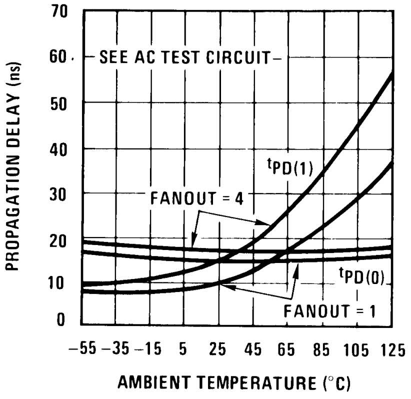
Typical Performance Characteristics

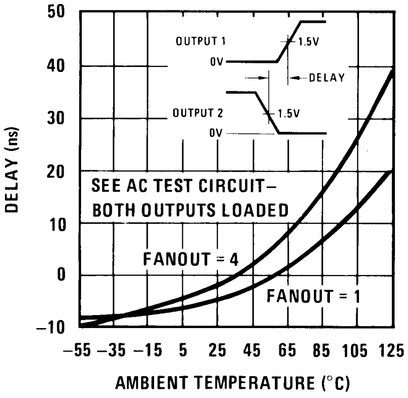

Offset Voltage


Input Current vs Ambient Temperature


Input Characteristics

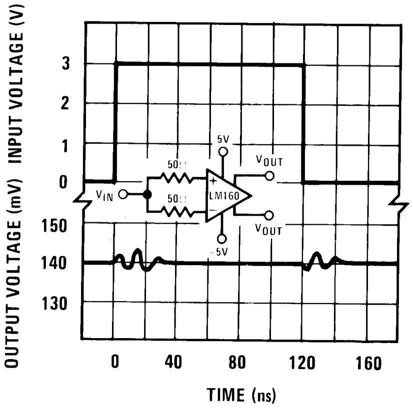

Supply Current vs Ambient Temperature


Propagation Delay vs Ambient Temperature

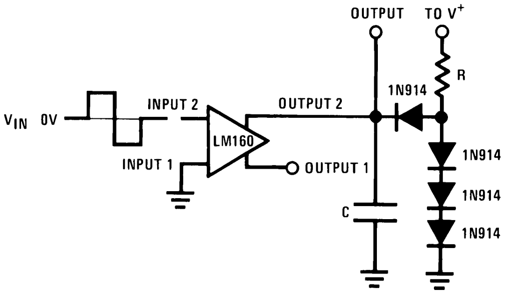

Delay of Output 1 With Respect to Output 2 vs Ambient Temperature

Typical Performance Characteristics (continued)

Common-Mode Pulse Response

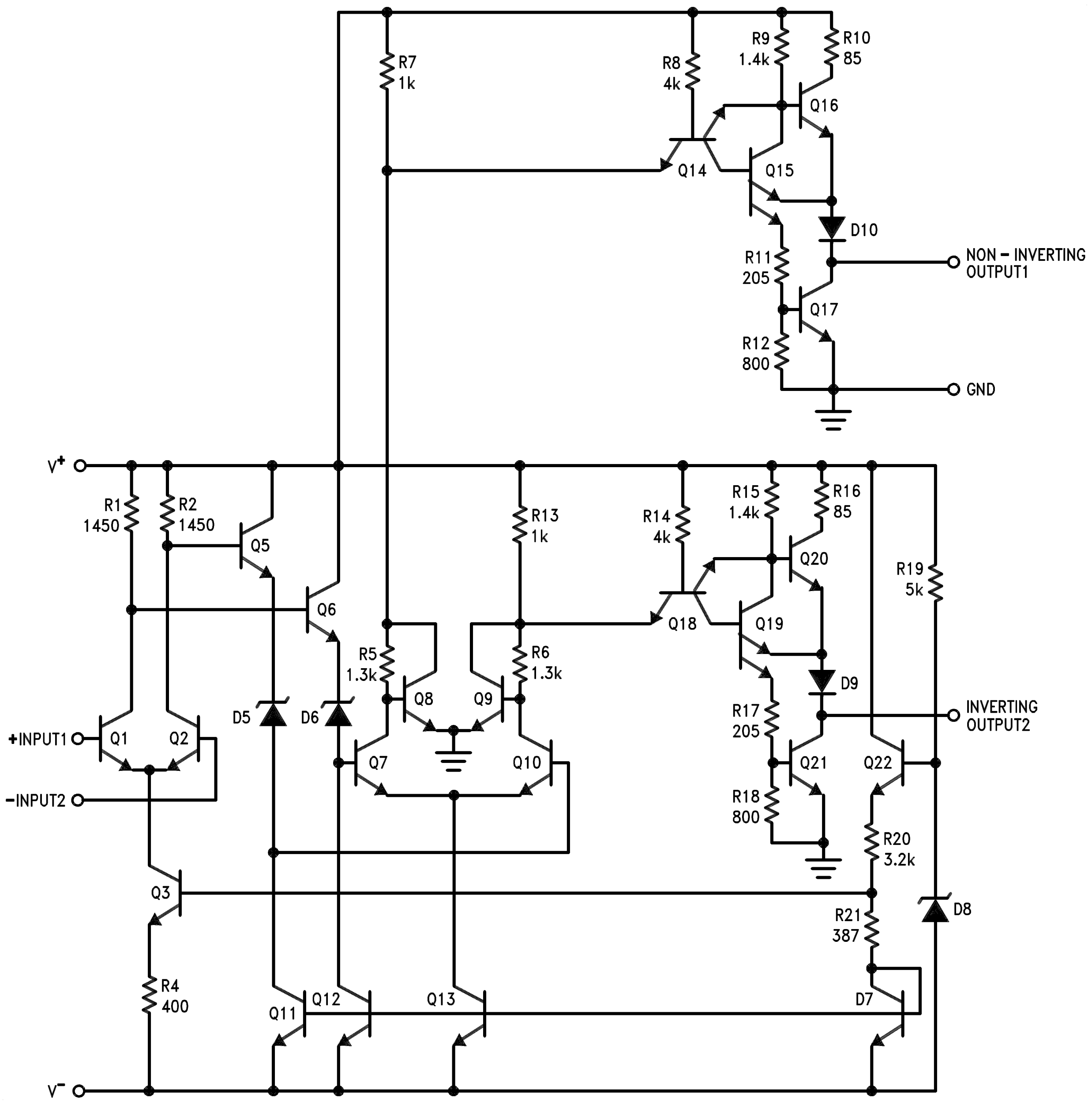


AC TEST CIRCUIT



V_{IN}=±50 mV	FANOUT=1	FANOUT=4
V^+=+5V	R=2.4k	R=630Ω
V^-=−5V	C=15 pF	C=30 pF

SCHEMATIC DIAGRAM



PACKAGE OPTION ADDENDUM

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM360M	ACTIVE	SOIC	D	8	95	TBD	CU SNPB	Level-1-235C-UNLIM	0 to 70	LM 360M	Samples
LM360M/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM 360M	Samples
LM360MX	ACTIVE	SOIC	D	8	2500	TBD	CU SNPB	Level-1-235C-UNLIM	0 to 70	LM 360M	Samples
LM360MX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM 360M	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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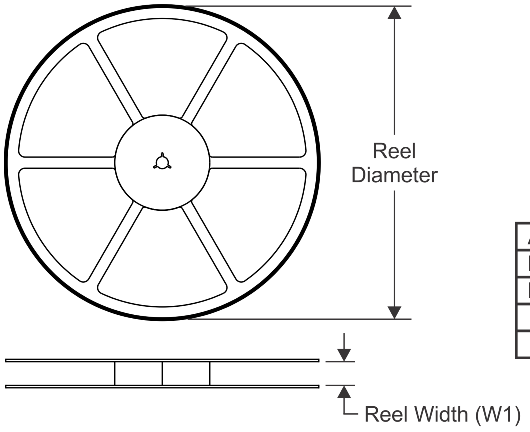
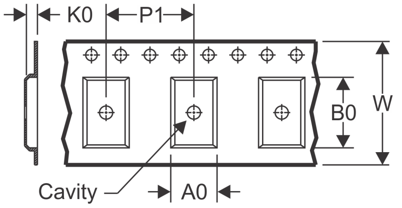
TAPE AND REEL INFORMATION

REEL DIMENSIONS

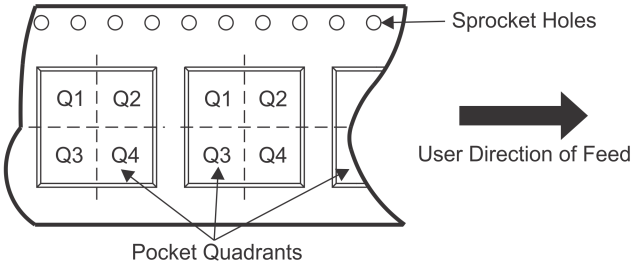


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

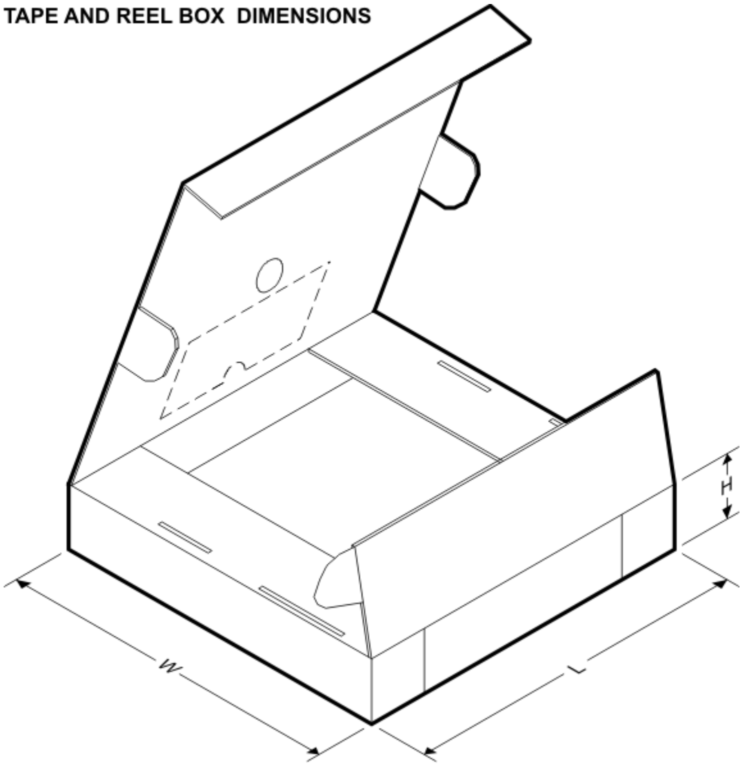
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM360MX	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM360MX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1

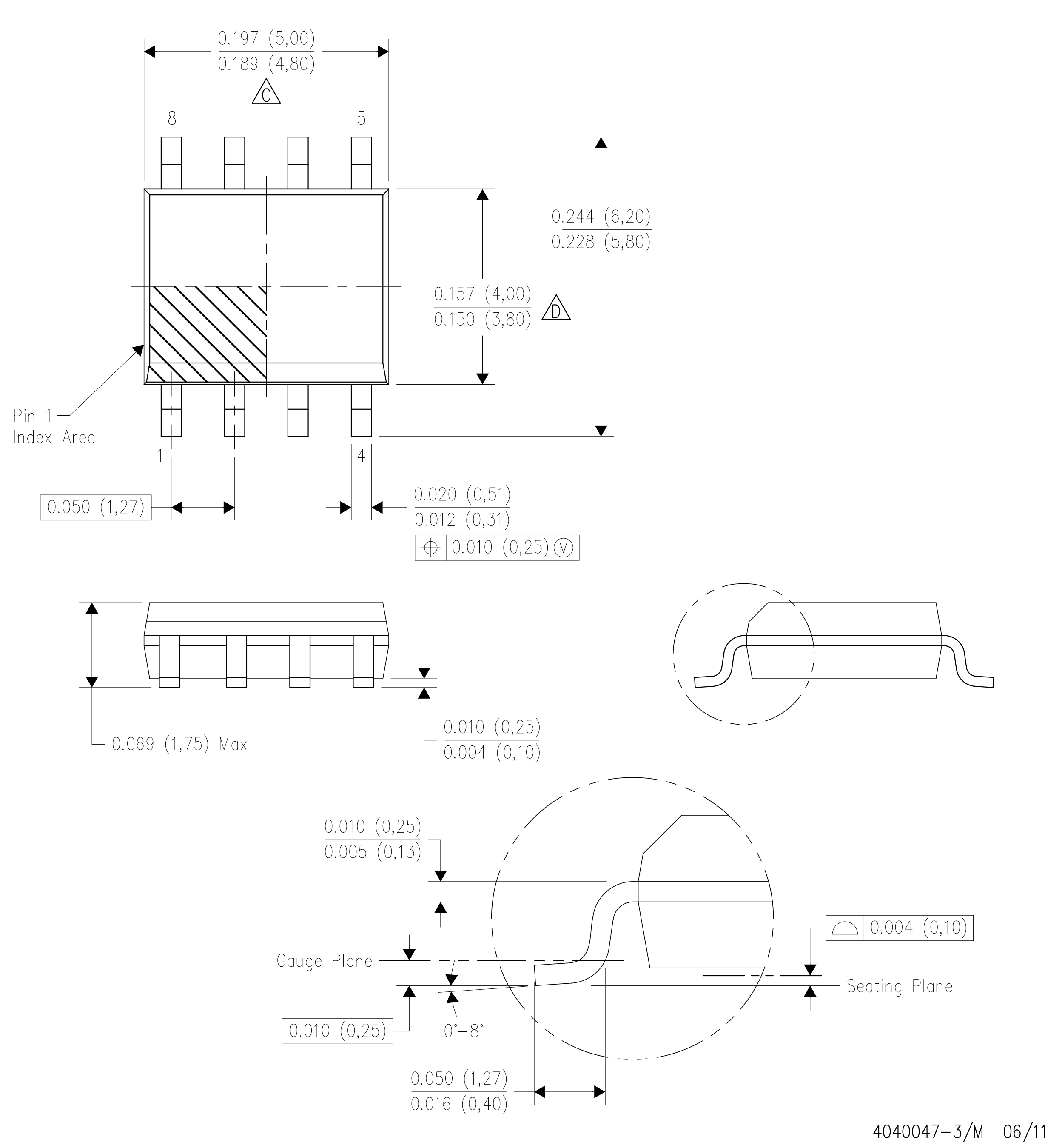
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM360MX	SOIC	D	8	2500	349.0	337.0	45.0
LM360MX/NOPB	SOIC	D	8	2500	349.0	337.0	45.0

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.

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